

IN THE CLAIMS:

Please amend the claims as follows:

- C,
1. (Currently Amended) A platform to support one or more semiconductor substrate processing cells, comprising:
 - a lower mainframe;
 - an upper mainframe including a plurality of recesses, ~~each one of the plurality of recesses configured~~ positioned to receive [a] the semiconductor substrate processing cells; and
 - a substrate-handling robot disposed on the upper mainframe to transfer a plurality of semiconductor substrates between the semiconductor substrate processing cells; and
 - a plurality of supporting members disposed between the lower mainframe and the upper mainframe, wherein each supporting member comprises sand.
 2. (Currently Amended) The platform of claim 1, wherein the upper mainframe further comprises a fastener structure positioned proximate each one of the recesses, wherein the fastener structure is ~~configured~~ positioned to hold the semiconductor substrate processing cells.
 3. (Previously Presented) The platform of claim 1, wherein the upper mainframe further comprises a rigidifying plate and a main base plate comprising the plurality of recesses, the rigidifying plate comprising at least one aperture and attached to the main base plate such that the at least one aperture is aligned with the recesses.
 4. (Currently Amended) The platform of claim 1, wherein the semiconductor substrate processing cells [is] comprise a deposition process cell.
 5. (Currently Amended) The platform of claim 1, wherein the semiconductor substrate processing cells [is] comprise a metrology cell.

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6. (Currently Amended) The platform of claim 1, wherein the semiconductor substrate processing cells [is] comprise an SRD cell.

7. (Cancelled)

8. (Currently Amended) A platform to support one or more semiconductor substrate processing cells, comprising:

a lower mainframe;

an upper mainframe including a plurality of recesses, ~~each one of the plurality of recesses configured~~ positioned to receive [a] the semiconductor substrate processing cells; and

a substrate-handling robot disposed on the upper mainframe to transfer a plurality of substrates between the semiconductor substrate processing cells; and

a plurality of support members between the lower mainframe and the upper mainframe, wherein each support member comprises:

a hollow tubular member;

a piston slidably disposed within the hollow tubular member; and

a dampening element contained within the hollow tubular member, wherein the piston is biased against the dampening element.

9. (Original) The platform of claim 8, wherein the dampening element is sand.

10. (Original) The platform of claim 8, wherein the dampening element acts as a vibration dampener.

11. (Currently Amended) A platform to support [a] one or more cells, comprising:

a lower mainframe;

an upper mainframe including a plurality of recesses, ~~each one of the plurality of recesses configured~~ positioned to receive [a] the cells;

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a substrate-handling robot disposed on the upper mainframe to transfer a plurality of substrates between the cells; and

a dampener system connecting the lower mainframe to the upper mainframe, wherein the dampener system comprises a plurality of support members that extend between the lower mainframe and the upper mainframe, each support member comprises:

a hollow tubular member,

a piston slidably disposed within the hollow tubular member, and

a dampening element contained within the hollow tubular member,

wherein the piston is biased against the dampening element.

12. (Currently Amended) ~~The platform of claim 11~~ A platform to support a cell, comprising:

a lower mainframe;

an upper mainframe including a plurality of recesses, each one of the plurality of recesses configured to receive a cell, wherein the upper mainframe further comprises a fastener structure positioned proximate each one of the recesses, wherein the fastener structure is configured to hold the cell; and

a dampener system connecting the lower mainframe to the upper mainframe, wherein the dampener system comprises a plurality of support members that extend between the lower mainframe and the upper mainframe, wherein each support member comprises:

a hollow tubular member,

a piston slidably disposed within the hollow tubular member, and

a dampening element contained within the hollow tubular member,

wherein the piston is biased against the dampening element.

13. (Currently Amended) ~~The platform of claim 11~~ A platform to support a cell, comprising:

a lower mainframe;

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an upper mainframe including a plurality of recesses, each one of the plurality of recesses configured to receive a cell, wherein the upper mainframe further comprises a rigidifying plate and a main base plate comprising the plurality of recesses, the rigidifying plate comprising at least one aperture and attached to the main base plate such that the at least one aperture is aligned with the recesses; and

a dampener system connecting the lower mainframe to the upper mainframe, wherein the dampener system comprises a plurality of support members that extend between the lower mainframe and the upper mainframe, wherein each support member comprises:

a hollow tubular member,

a piston slidably disposed within the hollow tubular member, and

a dampening element contained within the hollow tubular member,

wherein the piston is biased against the dampening element.

14. (Original) The platform of claim 11, wherein the cell is a process cell.
15. (Original) The platform of claim 11, wherein the cell is a metrology cell.
16. (Original) The platform of claim 11, wherein the cell is a SRD cell.
17. (Cancelled)
18. (Currently Amended) The platform of claim 20, wherein the upper mainframe further comprises a fastener means positioned proximate each one of the recesses, wherein the fastener means is ~~configured~~ positioned to hold the semiconductor substrate processing cell.
19. (Previously Presented) The platform of claim 20, wherein the upper mainframe further comprises a rigidifying plate and a main base plate comprising the plurality of recesses, the rigidifying plate comprising at least one aperture and attached to the main base plate such that the at least one aperture is aligned with the recesses.

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20. (Currently Amended) A platform to support one or more semiconductor substrate processing cells, comprising:

a lower mainframe;

an upper mainframe including a plurality of recesses, ~~each one of the plurality of recesses configured~~ positioned to receive [a] the semiconductor substrate processing cells;

a substrate-handling robot disposed on the upper mainframe to transfer a plurality of substrates between the cells; and

a dampener means disposed between the lower mainframe to the upper mainframe to support the upper mainframe relative to the lower mainframe, wherein the dampener means comprises ~~a dampening element, the dampening element being sand.~~

21. (Previously Presented) The platform of claim 20, wherein the dampener means comprises a plurality of supporting means that extends between the lower mainframe and the upper mainframe.
